RELIABILITY REPORT
FOR
MAX262ACNG+
PLASTIC ENCAPSULATED DEVICES

November 4, 2009

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX262ACNG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

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I. Device Description

A. General

The MAX260/MAX261/MAX262 CMOS dual second-order universal switched-capacitor active filters allow microprocessor control of precise filter functions. No external components are required for a variety of bandpass, lowpass, highpass, notch, and allpass configurations. Each device contains two second-order filter sections that place center frequency, Q, and filter operating mode under programmed control. An input clock, along with a 6-bit f0 program input, determine the filter’s center or corner frequency without affecting other filter parameters. The filter Q is also programmed independently. Separate clock inputs for each filter section operate with either a crystal, RC network, or external clock generator. The MAX260 has offset and DC specifications superior to the MAX261 and MAX262 and a center frequency (f0) range of 7.5kHz. The MAX261 handles center frequencies to 57kHz, while the MAX262 extends the center frequency range to 140kHz by employing lower clock-to-f0 ratios. All devices are available in 24-pin DIP and small outline packages in commercial, extended, and military temperature ranges.
II. Manufacturing Information
A. Description/Function: Microprocessor Programmable Universal Active Filters
B. Process: SG5
C. Number of Device Transistors: 
D. Fabrication Location: Oregon
E. Assembly Location: Philippines
F. Date of Initial Production: Pre 1997

III. Packaging Information
A. Package Type: 24-pin PDIP
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive Epoxy
E. Bondwire: Gold (1.3 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-0201-0039
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C Level 1
J. Single Layer Theta Ja: 75°C/W
K. Single Layer Theta Jc: 30°C/W
L. Multi Layer Theta Ja: °C/W
M. Multi Layer Theta Jc: °C/W

IV. Die Information
A. Dimensions: 199 X 132 mils
B. Passivation: Si₃N₄/SiO₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect: Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization: None
E. Minimum Metal Width: 5.0 microns (as drawn)
F. Minimum Metal Spacing: 5.0 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO₂
I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

   The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

   \[
   \lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 550 \times 2}
   \]

   (Chi square value for MTTF upper limit)

   \[
   (\text{where } 4340 = \text{Temperature Acceleration factor assuming an activation energy of } 0.8 \text{eV})
   \]

   \[
   \lambda = x 10^{-9}
   \]

   \[
   \lambda = F.I.T. (60\% \text{ confidence level @ 25°C})
   \]

   The following failure rate represents data collected from Maxim’s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the SG5 Process results in a FIT Rate of 0.12 @ 25°C and 2.04 @ 55°C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

   The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

   The AF05-4 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-50 mA.
<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong> (Note 1)</td>
<td>Ta = 135°C Biased Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>550</td>
<td>0</td>
</tr>
<tr>
<td><strong>Moisture Testing</strong> (Note 2)</td>
<td>HAST Ta = 130°C RH = 85% Biased Time = 96hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td><strong>Mechanical Stress</strong> (Note 2)</td>
<td>Temperature Cycle -65°C/150°C 1000 Cycles Method 1010</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data